

OSXX0805C1E

Features

- Single chip
- 2.0x1.25x0.8mm(0805) standard package.
- Suitable for all SMT assembly methods.
- Compatible with infrared and vapor phase reflow solder process.
- This product doesn't contain restriction Substance, comply ROHS standard.
- Compatible with automatic placement equipment.

Applications

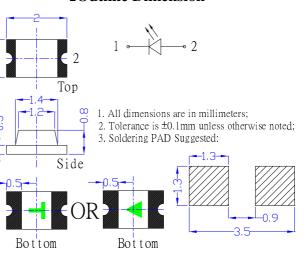
- Automotive : Dashboards, stop lamps, turn signals.
- Backlighting : LCDs, Key pads advertising.

Absolute Maximum Rating

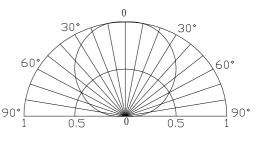
(Ta=25℃)

(Ta=25°C)

Item	Course had	Valu	TI-::4			
пеш	Symbol	W/M/B/V/K/G5	R/Y/O/G8	Unit		
DC Forward Current	I_{F}	30	30	mA		
Pulse Forward Current*	I_{FP}	100	100	mA		
Reverse Voltage	VR	5	5	V		
Power Dissipation	PD	108	78	mW		
Operating Temperature	Topr	-40 ~ +85				
Storage Temperature	Tstg	-40~ +85				
Lead Soldering Temperature	Tsol	260°C/1	-			



Directivity



*Pulse width Max 0.1ms, Duty ratio max 1/10

■Electrical -Optical Characteristics

			$V_{\rm F}\left({ m V} ight)$		$I_R(\mu A)$	Iv(mcd)		λD(nm)		2θ1/2(deg)				
Part Number Color		Color		Min.	Тур.	Max.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	Тур.
		I _F =20mA		V _R =5V	I _F =20mA									
OSW50805C1E	White	W5		-	3.3	3.6	10	350	450	-	X:0.27, Y:0.28		120	
OSM50805C1E	Warm White	M5		-	3.3	3.6	10	350	450	-	X:0.44, Y:0.41		120	
OSK50805C1E	Pink	K5		-	3.3	3.6	10	60	90	-	X:0.38, Y:0.18		120	
OSV40805C1E	Violet	V4			3.3	3.6	10	8	12	-	395	400	405	120
OSB50805C1E	Blue	B5		-	3.2	3.6	10	80	120	-	460	465	475	120
OSG50805C1E	True Green	G5			3.3	3.6	10	400	450	-	520	525	530	120
OSG80805C1E	Yellow Green	G8		-	2.0	2.6	10	20	35	-	564	570	578	120
OSY50805C1E	Yellow	Y5		-	2.1	2.6	10	100	120	-	585	590	595	120
OSO50805C1E	Orange	05		-	2.0	2.6	10	100	120	-	600	605	610	120
OSR50805C1E	Red	R5		-	2.0	2.6	10	120	150	-	620	625	630	120

*1 Tolerance of measurements of chromaticity coordinate is $\pm 10\%$

*2 Tolerance of measurements of dominant wavelength is ± 1 nm

*3 Tolerance of measurements of luminous intensity is $\pm 15\%$

*4 Tolerance of measurements of forward voltage is±0.1V

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•Outline Dimension

2.0x1.25x0.8mm Chip LED



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Cautions:

1. After open the package, the LED's floor life is 1 year under 30° C or less and 60%RH or less (MSL:2).

2. Heat generation must be taken into design consideration when using the LED.

3. Power must be applied resistors for protection, over current would be caused the optic damage to the devices and wavelength shift.

4. Manual tip solder may cause the damage to Chip devices, so advised that heat of iron should be lower than 15W with temperature control under 5 seconds at 230-260 deg. C. (The device would be got damage in re working process, recommended under 5 seconds at 230-260 deg. C)

5. All equipment and machinery must be properly grounded. It is recommended to use a wristband or anti-electrostatic glove when handing the LED.

6. Use IPA as a solvent for cleaning the LED. The other solvent may dissolve the LED package and the epoxy, Ultrasonic cleaning should not be done.

7. Damaged LED will show unusual characteristics such as leak current remarkably increase, turn-on voltage becomes lower and the LED get unlight at low current.

8. OPTOSUPPLY will not do 4M change without advance consultation.

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